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(71) Applicant: **NANYANG TECHNOLOGICAL UNIVERSITY** [SG/SG]; 50 Nanyang Avenue, Singapore 639798 (SG).

(72) Inventors: **SUM, Tze Chien**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG). **LAM, Yeng Ming**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG). **YE, Senyun**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG). **RAO, Haixia**; c/o Nanyang Technological University, 50 Nanyang Avenue, Singapore 639798 (SG).

(74) Agent: **SPRUSON & FERGUSON (ASIA) PTE LTD**; P.O. Box 1531, Robinson Road Post Office, Singapore 903031 (SG).

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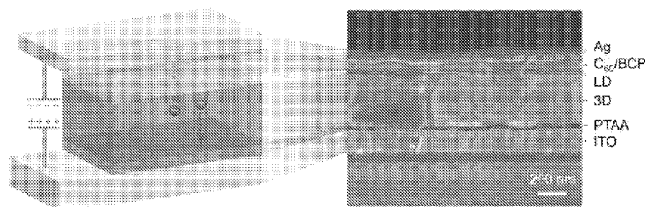
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(54) Title: INTERFACE MATERIALS FOR PEROVSKITES

Fig. 12A



(57) Abstract: The present disclosure relates to a device comprising: a) a three-dimensional perovskite compound layer; and b) a capping material layer comprising a capping material, provided on the three-dimensional perovskite compound layer. The present disclosure also relates to a method of preparing the device and the use of the device. Preferably, the capping material is a compound having a general formula $(A^2)_2M(X^2)_4$, $(A^2)_2(A^1)M_2(X^2)_7$, $(A^2)_mM_n(X^2)_{3n+m}$ or any mixture thereof and preferably is substantially free of Pb^{2+} or Sn^{2+} .

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